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May 2014

FDMA7632

Single N-Channel PowerTrench® MOSFET

30 V, 9 A, 19 m Ω

Features

- Max $r_{DS(on)} = 19 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 9 \text{ A}$
- Max $r_{DS(on)}$ = 30 m Ω at V_{GS} = 4.5 V, I_D = 7 A
- Low Profile 0.8 mm maximum in the new package MicroFET 2x2 mm
- Free from halogenated compounds and antimony oxides
- RoHS compliant

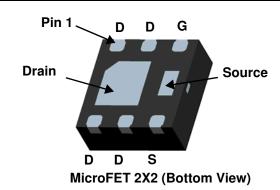


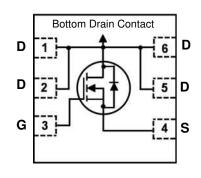
General Description

This device has been designed to provide maximum efficiency and thermal performance for synchronous buck converters. The low $r_{\text{DS(on)}}$ and gate charge provide excellent switching performance.

Application

■ DC – DC Buck Converters





MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol		Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage			30	V
V_{GSS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous	T _A = 25 °C	(Note 1a)	9	۸
	-Pulsed			24	Α
P _D	Power Dissipation	T _A = 25 °C	(Note 1a)	2.4	W
	Power Dissipation	T _A = 25 °C	(Note 1b)	0.9	VV
T _J , T _{STG}	Operating and Storage Junction T	Operating and Storage Junction Temperature Range			°C

Thermal Characteristics

R_{θ}	JA	Thermal Resistance, Junction to Ambient	(Note 1a)	52	°C/W
R_{θ}	JA	Thermal Resistance, Junction to Ambient	(Note 1b)	145	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
632	FDMA7632	MicroFET 2x2	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C	16			mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = 20 V, V _{DS} = 0 V			100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	2.1	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-6		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$		14	19	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 7 \text{ A}$		20	30	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}, T_J = 125 \text{ °C}$		19	25	
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 9 A		35		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 45 V V 0 V	570	760	pF
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1.0 MHz	195	260	pF
C _{rss}	Reverse Transfer Capacitance	1 – 1.0 1/11/2	25	40	pF
R_q	Gate Resistance		1.5		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time				6	12	ns
t _r	Rise Time	V _{DD} = 15 V, I _D = 9 A	$V_{DD} = 15 \text{ V}, I_{D} = 9 \text{ A}$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		2	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN} =			14	25	ns
t _f	Fall Time				2	10	ns
Q_q	Total Gate Charge	V _{GS} = 0 V to 10 V			9.3	13	nC
Q_q	Total Gate Charge	V _{GS} = 0 V to 4.5 V	V _{DD} = 15 V,		4.4	6	nC
Q_{gs}	Gate to Source Gate Charge		I _D = 9 A		1.9		nC
Q_{qd}	Gate to Drain "Miller" Charge				1.5		nC

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain-Source Diode Forward Current				2	Α
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2 \text{ A}$	(Note 2)	0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _E = 9 A, di/dt = 100 A/μs		18	32	ns
Q _{rr}	Reverse Recovery Charge	- I _F = 9 A, α//αι = 100 A/μs		5	10	nC

NOTES

^{1.} R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 52 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 145 °C/W when mounted on a minimum pad of 2 oz copper.

^{2.} Pulse Test: Pulse Width < 300 $\mu s,$ Duty cycle < 2.0%.

Typical Characteristics T_J = 25°C unless otherwise noted

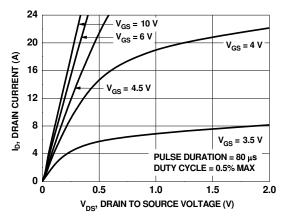


Figure 1. On-Region Characteristics

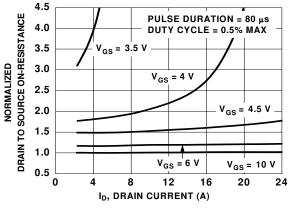


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

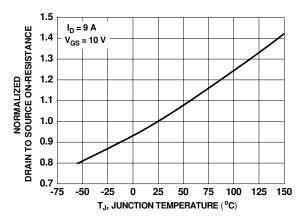


Figure 3. Normalized On-Resistance vs Junction Temperature

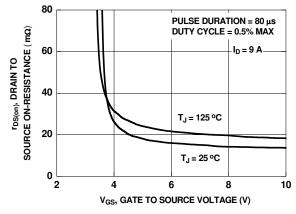


Figure 4. On-Resistance vs Gate to Source Voltage

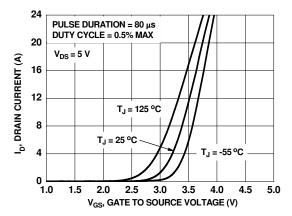


Figure 5. Transfer Characteristics

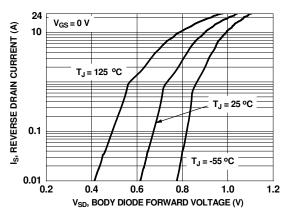


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

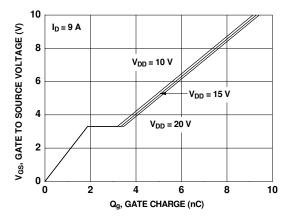


Figure 7. Gate Charge Characteristics

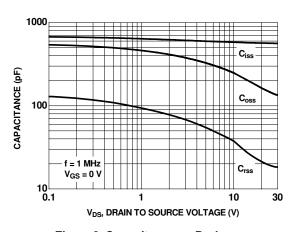


Figure 8. Capacitance vs Drain to Source Voltage

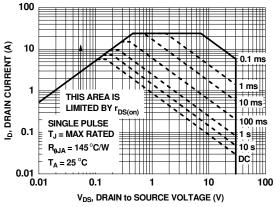


Figure 9. Forward Bias Safe Operating Area

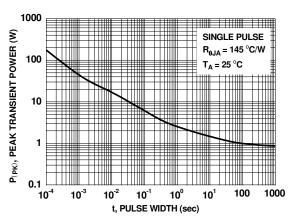


Figure 10. Single Pulse Maximum Power Dissipation

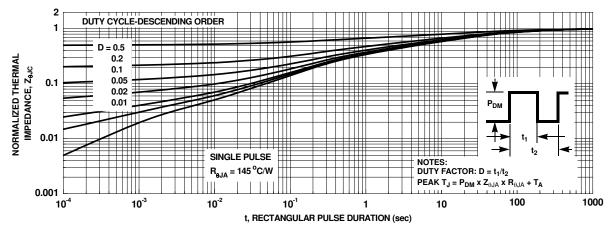
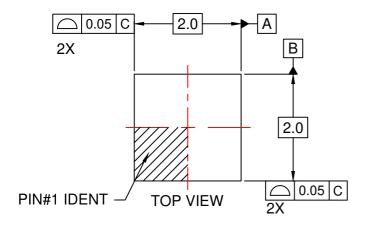
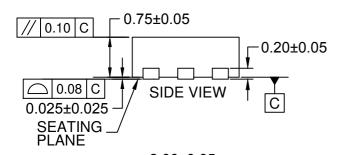
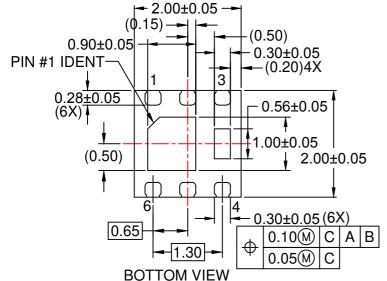


Figure 11. Transient Thermal Response Curve

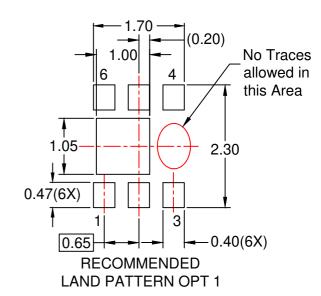


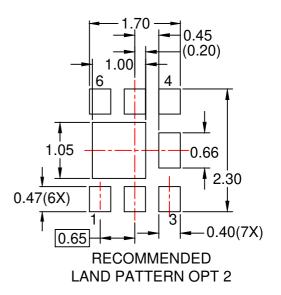




NOTES:

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